

# Challenges of SiC technology for high radiation hardness detectors

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# Outline

- Introduction
- Defects production by ion irradiation
  - Low fluence regime
  - High fluence regime
- Efficiency of point defects production
- SiC vs. Si radiation hardness
- Challenge for SiC detectors production
- Conclusions

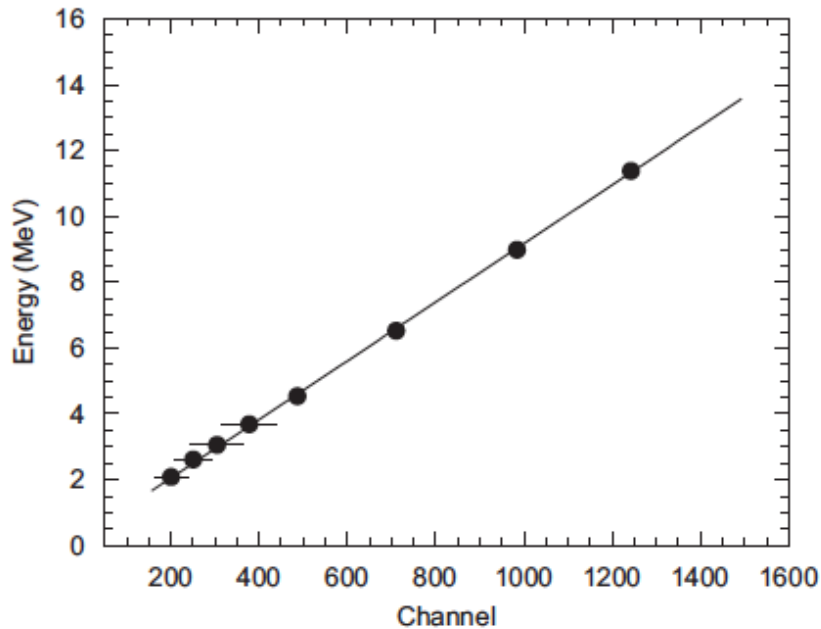
# Introduction

M.Moll , NIM in Physics Research A 511 (2003) 97–105

| Property                     | Diamond          | GaN            | 4H SiC           | Si               |
|------------------------------|------------------|----------------|------------------|------------------|
| $E_g$ [eV]                   | 5.5              | 3.39           | 3.26             | 1.12             |
| $E_{breakdown}$ [V/cm]       | $10^7$           | $4 \cdot 10^6$ | $2.2 \cdot 10^6$ | $3 \cdot 10^5$   |
| $\mu_e$ [ $cm^2/Vs$ ]        | 1800             | 1000           | 800              | 1450             |
| $\mu_h$ [ $cm^2/Vs$ ]        | 1200             | 30             | 115              | 450              |
| $v_{sat}$ [cm/s]             | $2.2 \cdot 10^7$ | -              | $2 \cdot 10^7$   | $0.8 \cdot 10^7$ |
| Z                            | 6                | 31/7           | 14/6             | 14               |
| $\epsilon_r$                 | 5.7              | 9.6            | 9.7              | 11.9             |
| e-h energy [eV]              | 13               | 8.9            | 7.6-8.4          | 3.6              |
| Density [g/cm <sup>3</sup> ] | 3.515            | 6.15           | 3.22             | 2.33             |
| Displacem. [eV]              | 43               | $\geq 15$      | 25               | 13-20            |

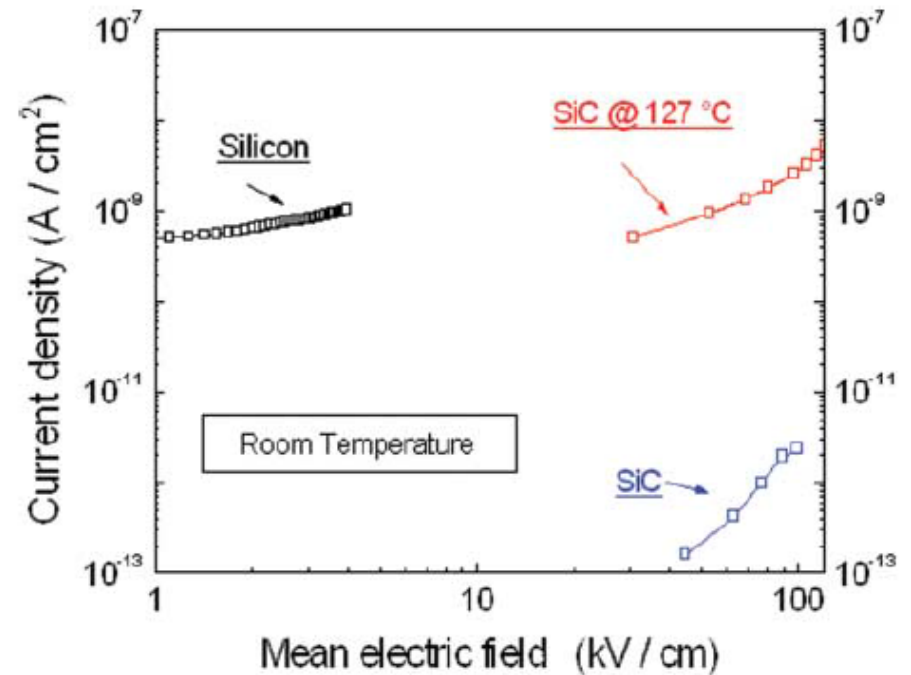
- Wide bandgap (3.3eV)  
⇒ lower leakage current than silicon
- Signal (for MIP !):  
Diamond 36 e/ $\mu m$   
SiC 51 e/ $\mu m$   
Si 89 e/ $\mu m$   
⇒ more charge than diamond Si/SiC $\approx 2$
- Higher displacement threshold than silicon  
⇒ radiation harder than silicon

# SiC detectors



*De Napoli et al. NIM A, 572 (2007), 831*  
*CNR-IMM detector*

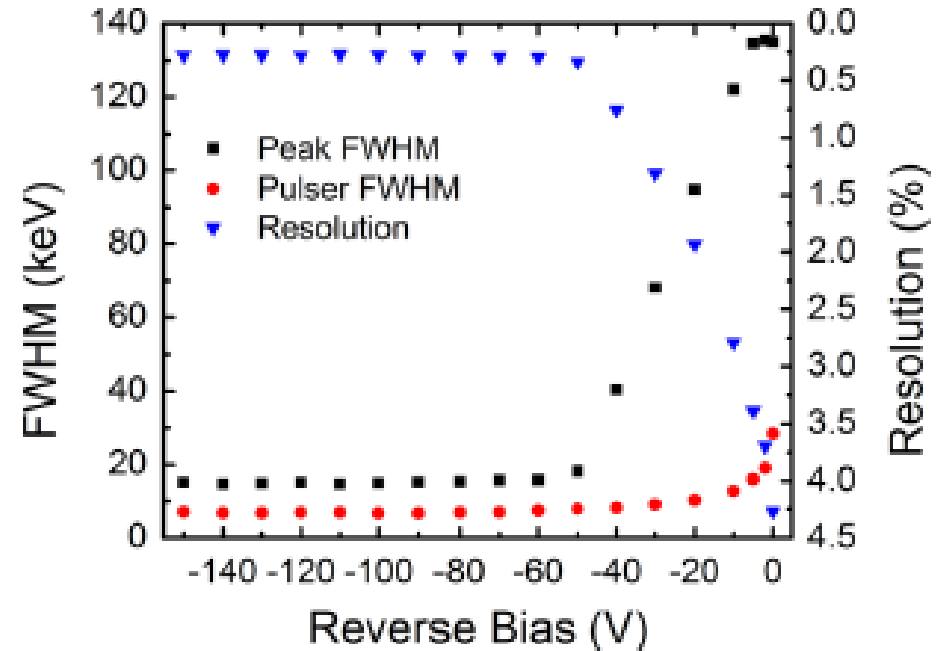
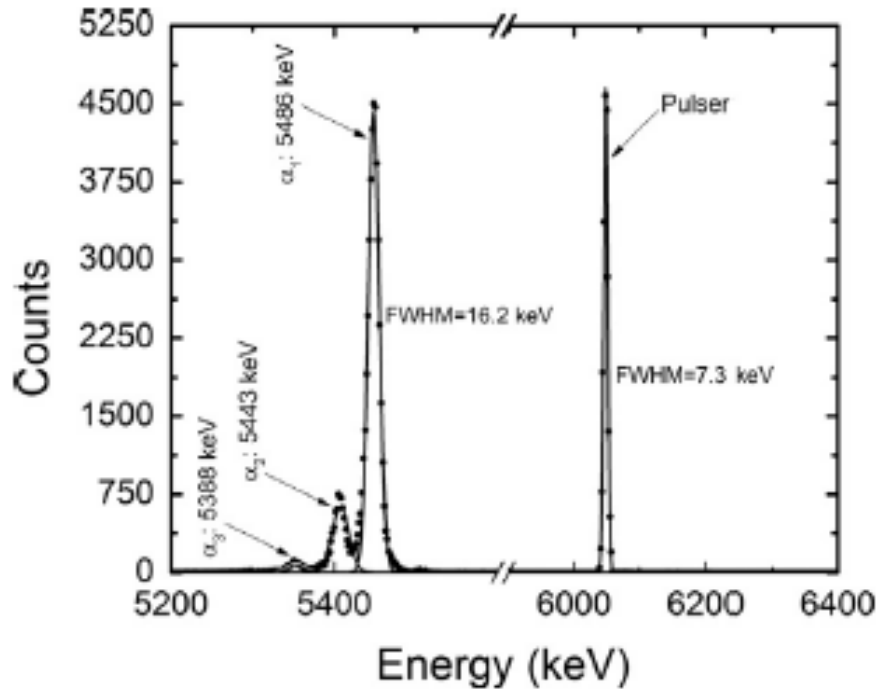
*High linearity*



*L. Calcagno et al. Radiation Effect & Defects in Solid, 170(4), (2015) 303*  
*CNR-IMM detector*

*Low noise*

# SiC detectors

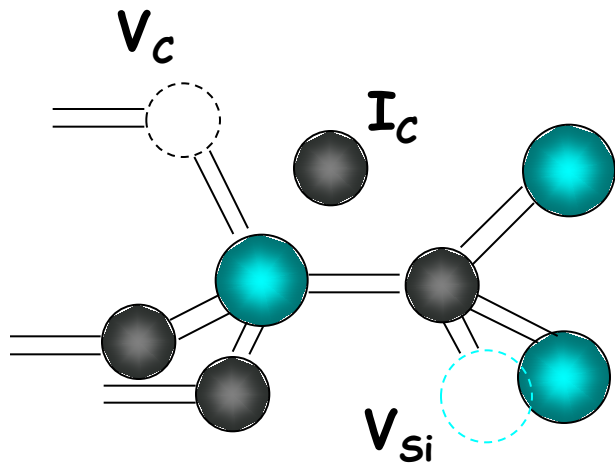


S.K. Chaudhuri et al. / Nuclear Instruments and Methods in Physics Research A 728 (2013) 97–101

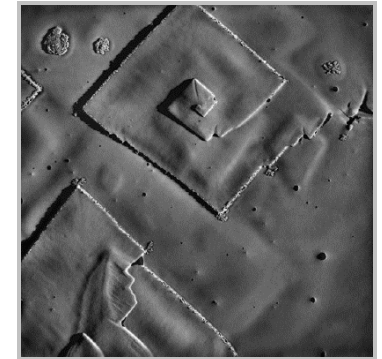
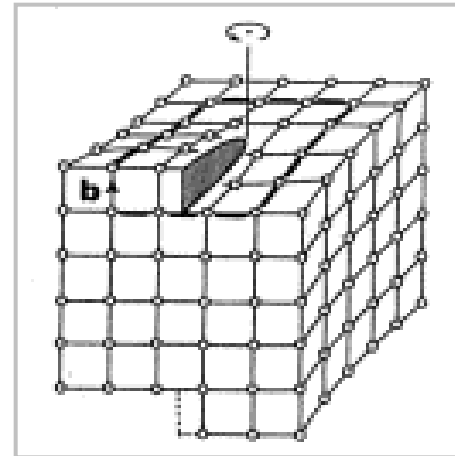
*Intrinsic detector resolution 14.5 KeV (0.2%)*

# Effects of ion irradiation

Ion irradiation can produce defects in the crystal lattice of the semiconductor



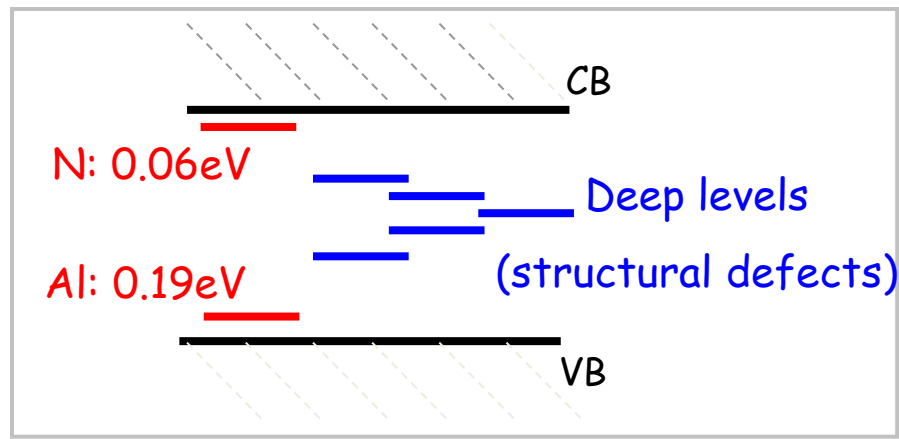
Point defects  
(vacancies, interstitial,  
antisites, etc...)



Extended defects  
(dislocations, etc...)

# Effect of defects on the detectors

The defects in the lattice produce some levels in the band-gap

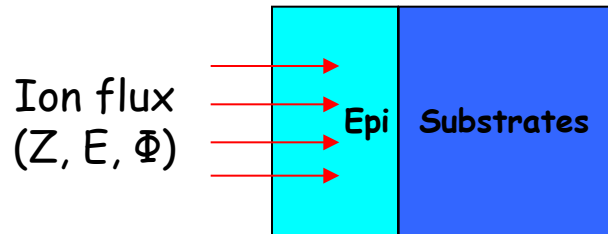


Increasing the density of these levels with the increasing of the ion dose, the characteristics of the detectors deteriorate

➡ Charge Collection Efficiency (CCE)

➡ Resolution (FWHM)

# Radiation induced defects



4H-SiC  
homo-epitaxial  
layers

Point defects  $< 10^{11} \text{ cm}^{-3}$   
Extended defects  $< 10^5 - 10^7 \text{ cm}^{-2}$

Low Fluence Regime:

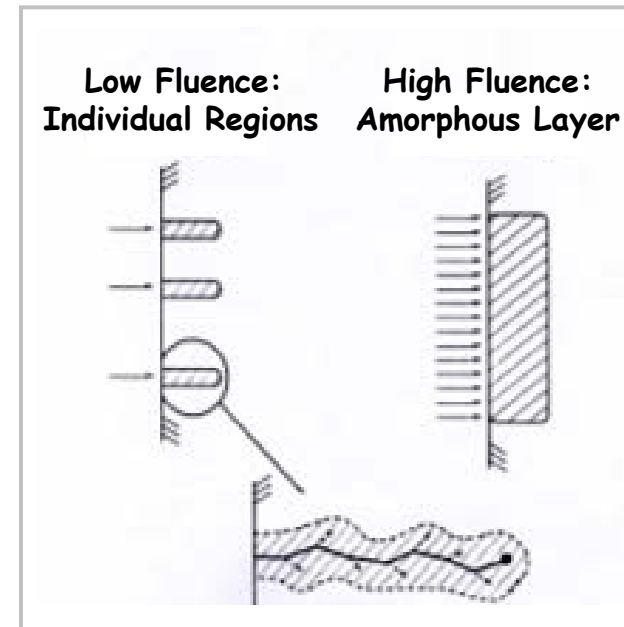
$$10^9 < \Phi < 10^{13} \text{ ions/cm}^2$$



point defects & defects cluster

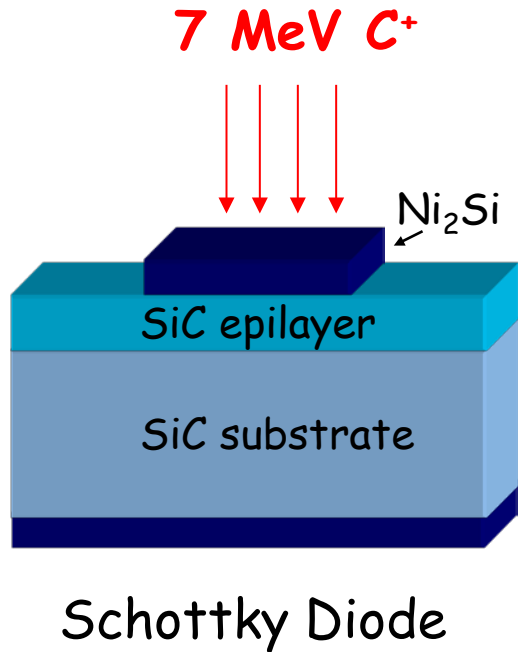
$$< 10^{18} \text{ defects/cm}^3$$

(DLTS, LTPL ...)



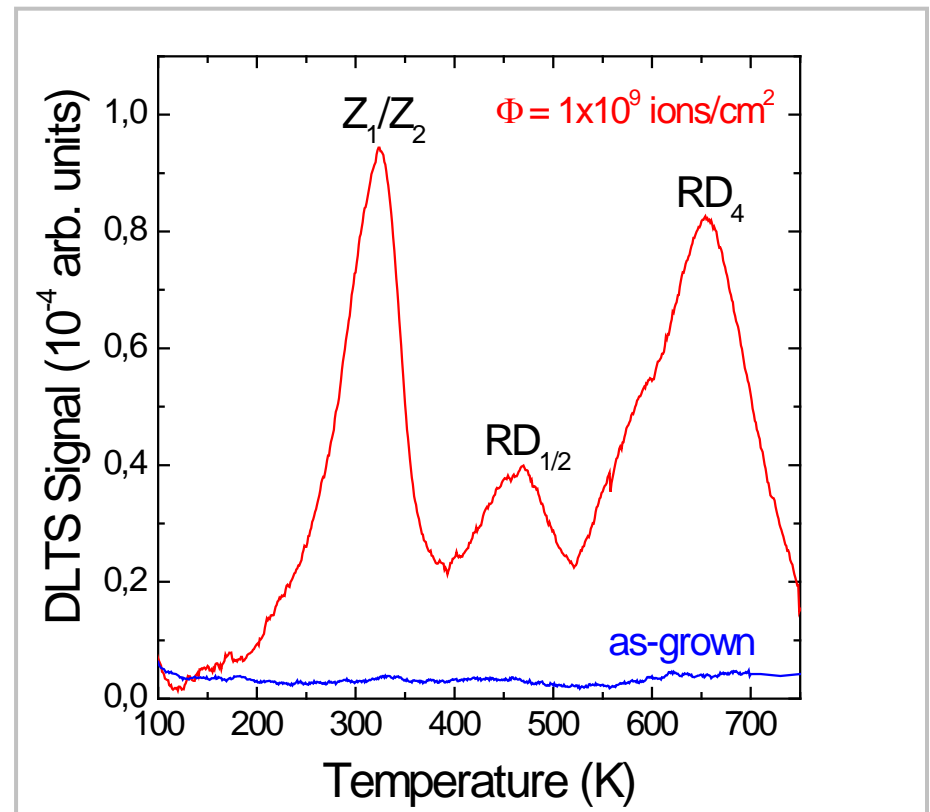


# Analisy of the radiation induced defects by DLTS

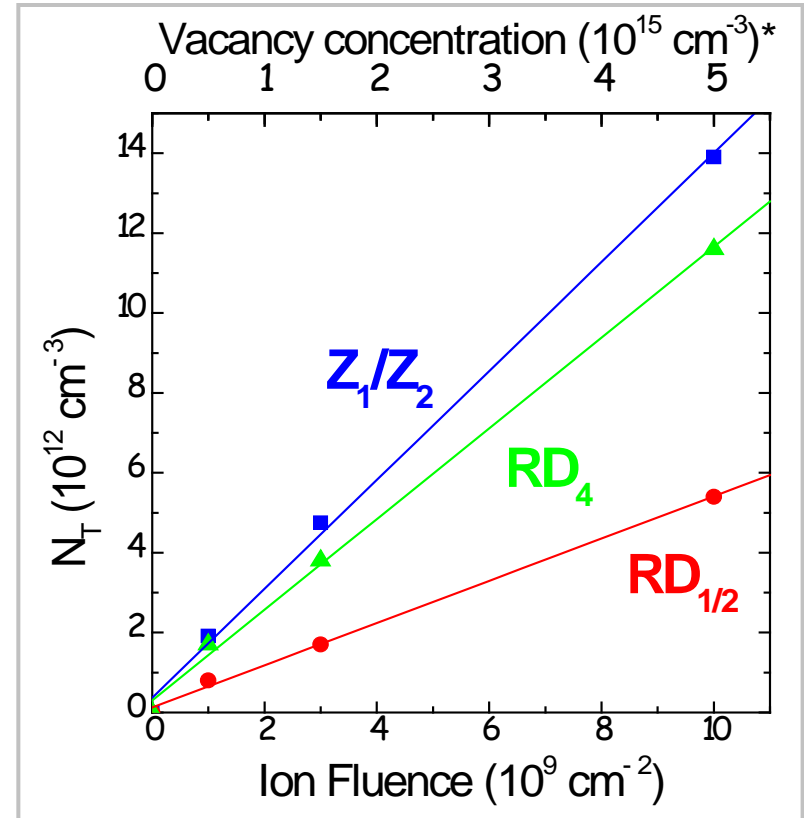
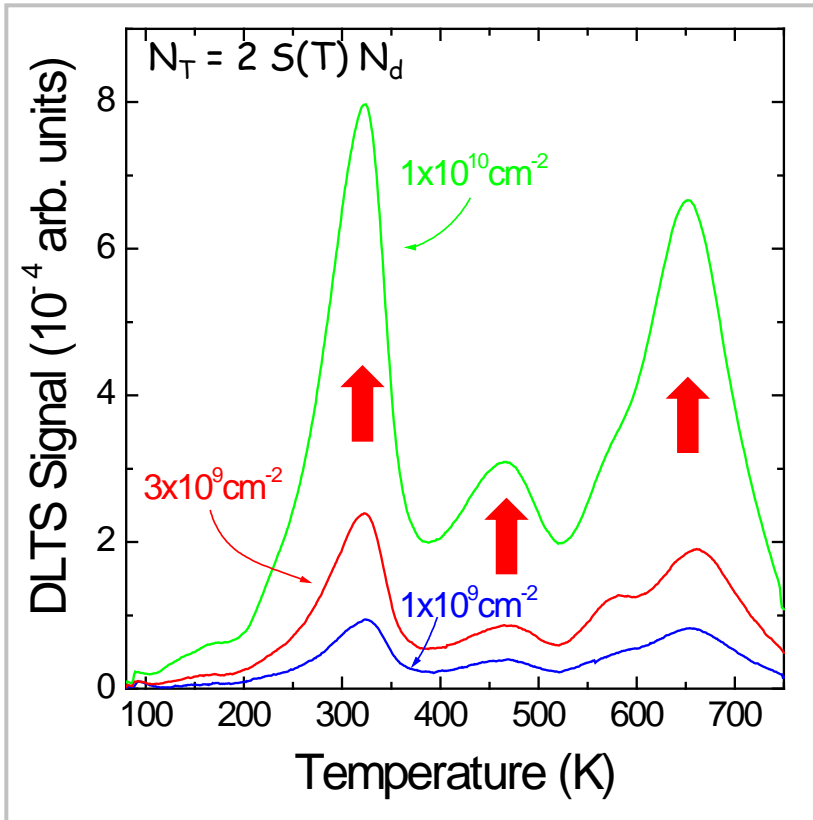


$$\Phi = 1 \times 10^9 - 5 \times 10^{13} \text{ ions/cm}^2$$

$$[V]^* = 10^{14} - 10^{19} \text{ vacancies/cm}^3$$



# Defects vs. ion dose



POINT DEFECTS {

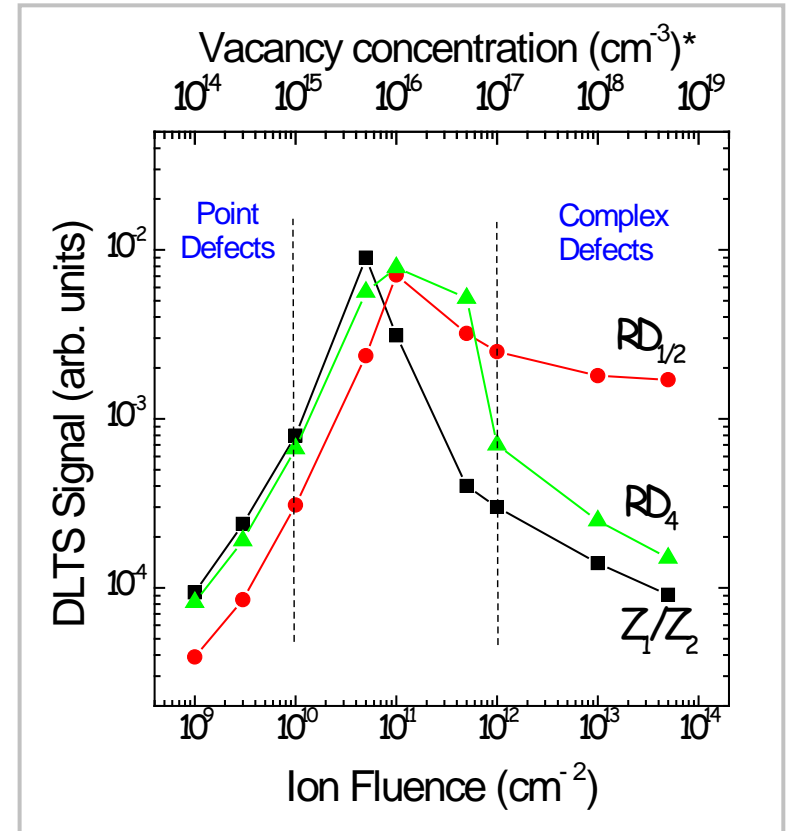
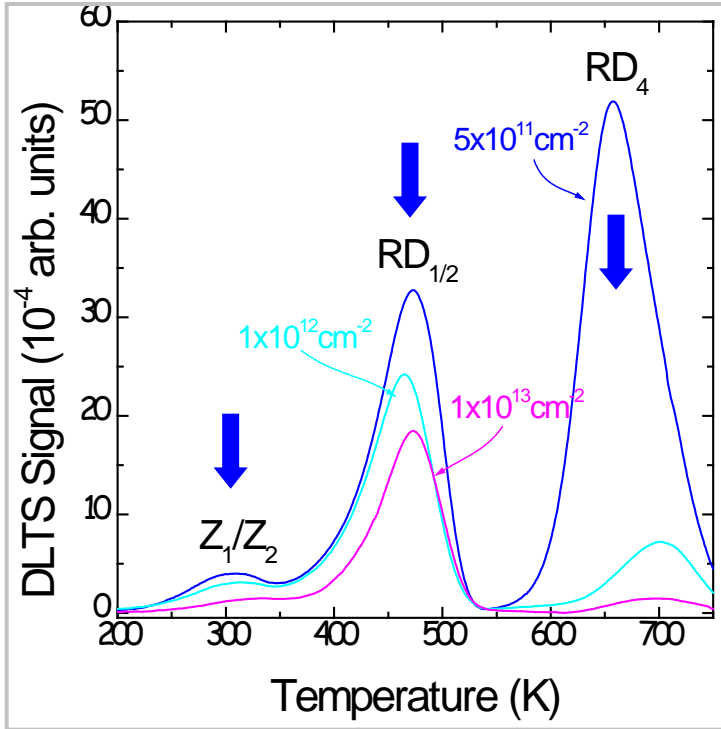
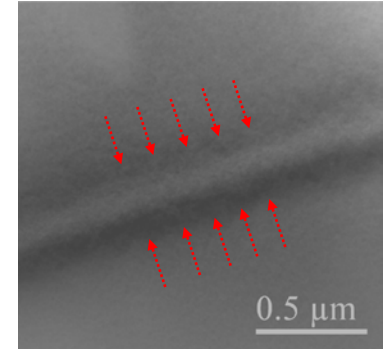
- $Z_1/Z_2: (V_{Si/C} Si_C C_{Si} C_i)**$
- $RD_{1/2}: (V_C + V_{Si})**$
- $RD_4: (V_C)**$

\*\* From literature

*Increasing ion dose the point defects increase linearly*

# High fluence regime

$$\Phi = 5 \times 10^{10} - 5 \times 10^{13} \text{ ions/cm}^2$$

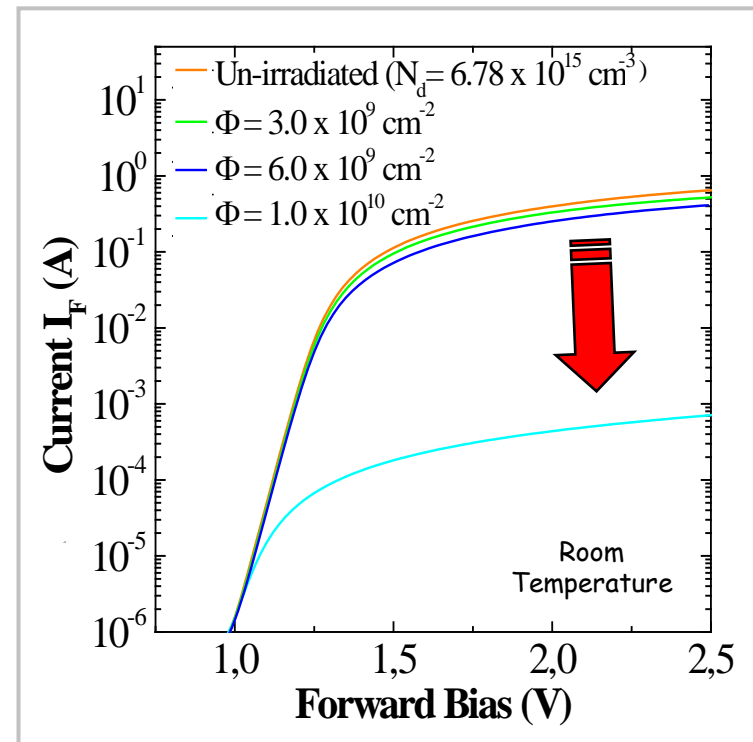
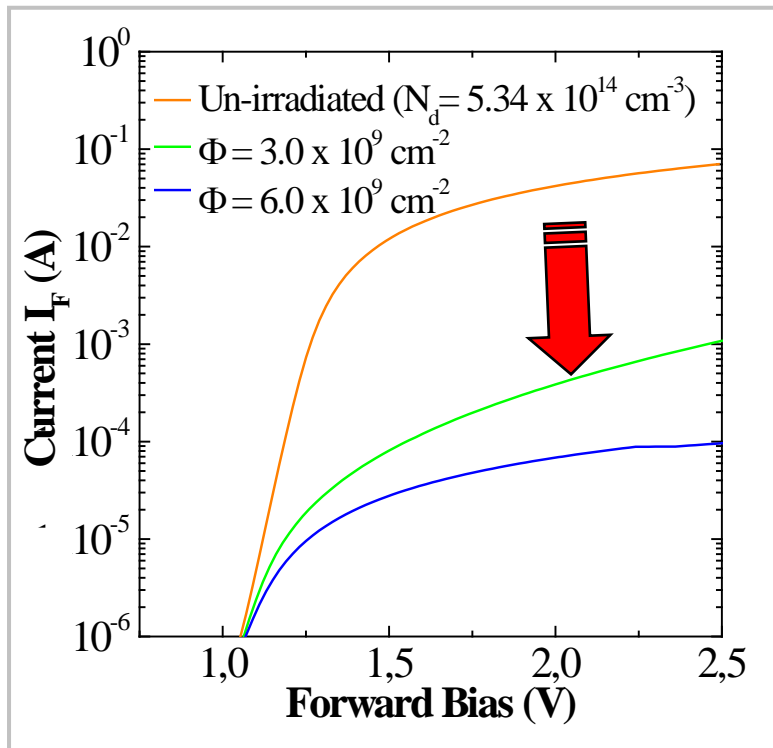


## POINT DEFECTS CLUSTERS

*G. Litrico et al. Mater. Sci. For. Vols. 615-617, (2009), pp. 397-400*

# Effect of radiation induced defect on I-V characteristics

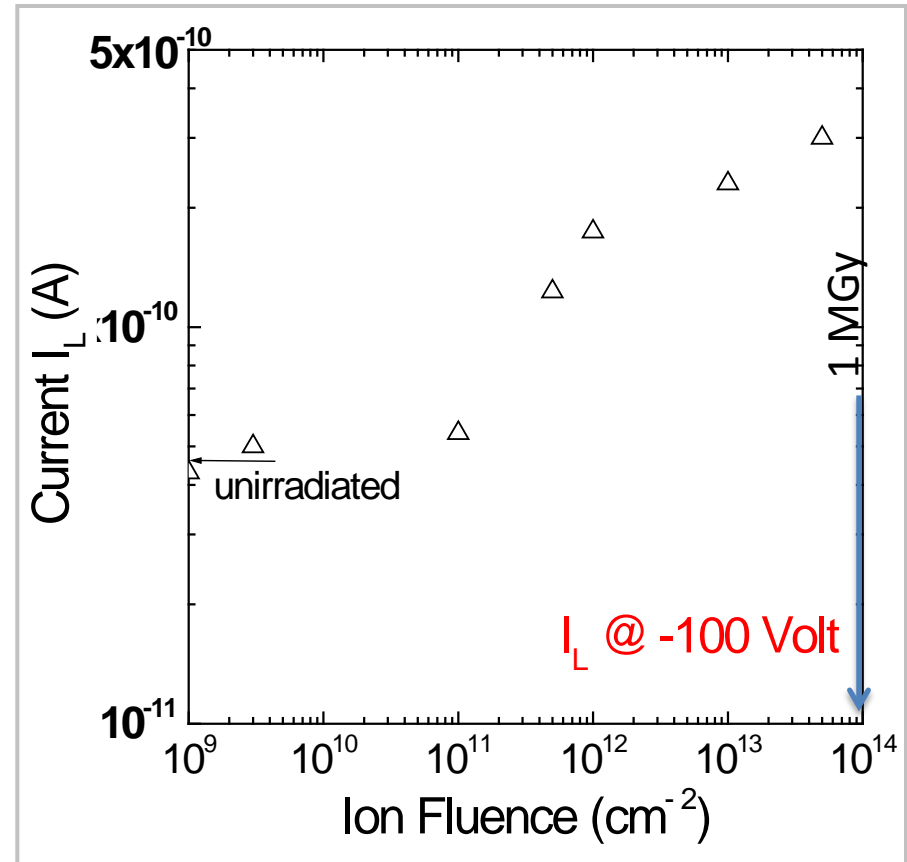
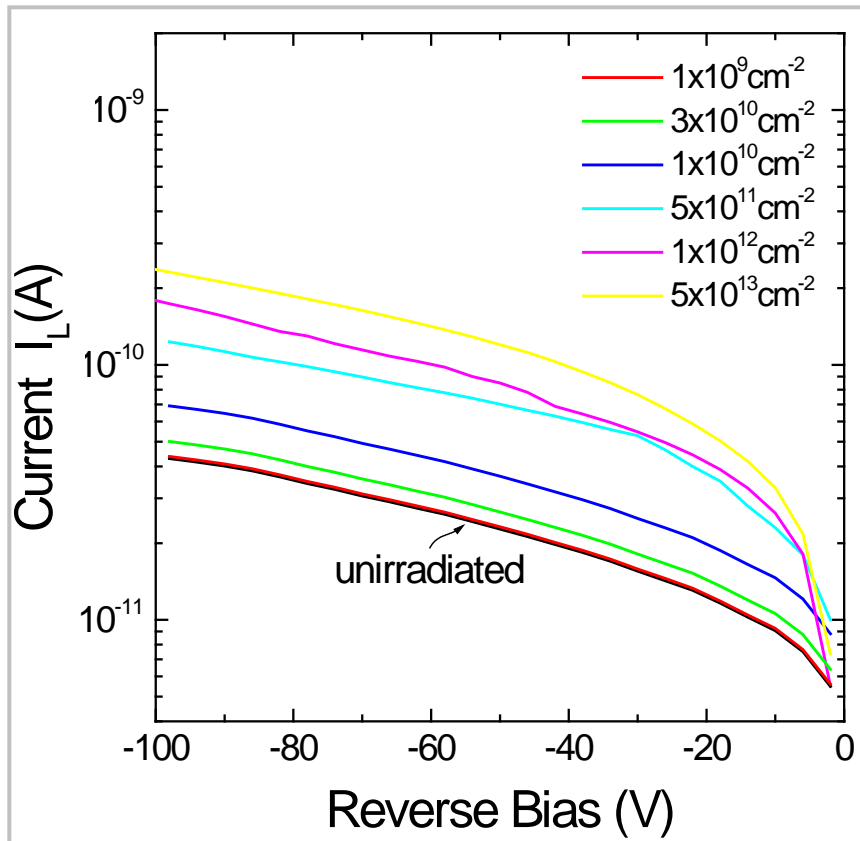
7 MeV C<sup>+</sup>



*Increasing the doping of the epitaxial layer the effect on the doping compensation decreases.*

*G. Litrico et al. J. Appl. Phys. Vol. 104 (2008) p. 093711*

# Effect of radiation induced defect on I-V characteristics



*A fluence of  $10^{14}/\text{cm}^2$  is needed to have an increase of the leakage current of one order of magnitude*

# Efficiency of point defects production

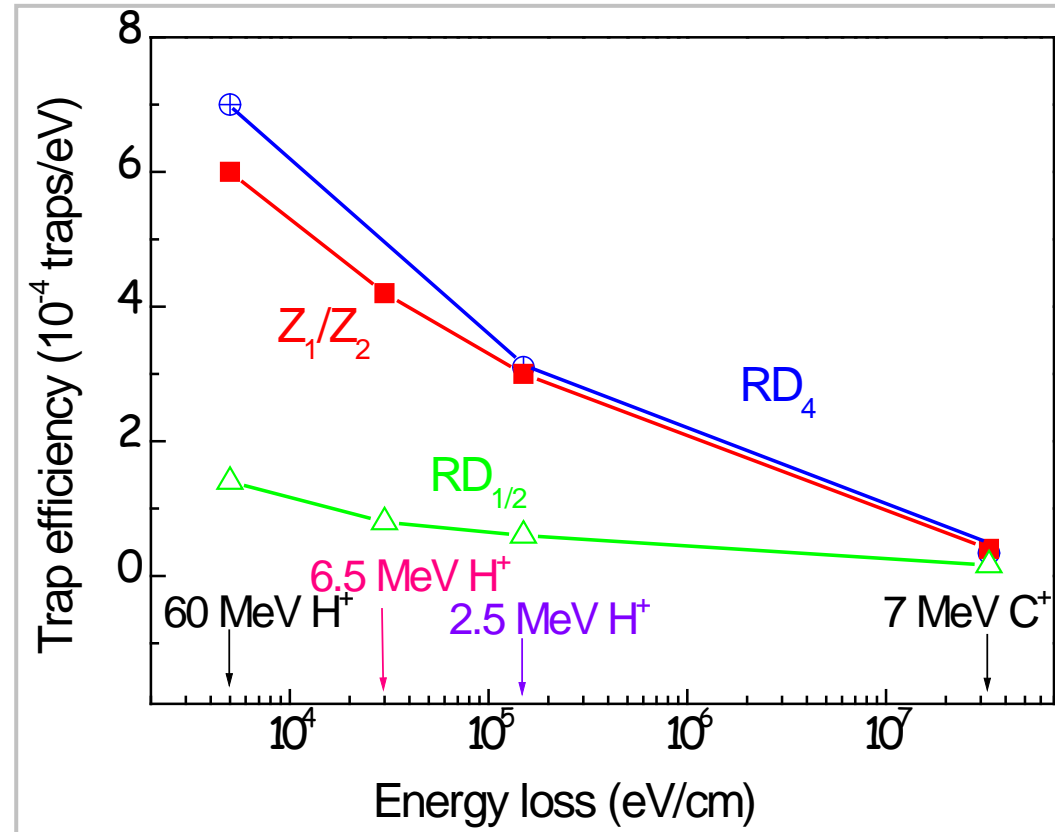
**INTRODUCTION RATE**  $\eta = \frac{N_T}{\Phi}$  [traps/cm]

- ion mass
- energy

$\eta (Z_1/Z_2)$  { 1363 traps/cm 7 MeV C<sup>+</sup>  
3 traps/cm 60 MeV H<sup>+</sup>

**TRAPS PRODUCTION EFFICIENCY**

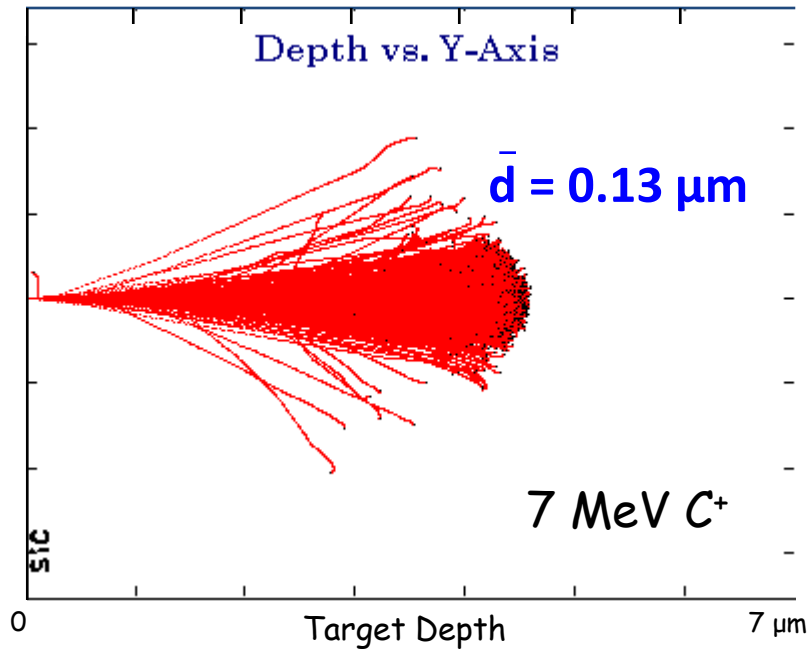
➔  $\epsilon = \frac{\eta}{S_n}$  [traps/eV]



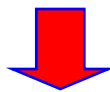
L. Calcagno et al. / Nucl. Instr. and Meth. in Phys. Res. B 257 (2007) 279–282

# Efficiency of point defects production

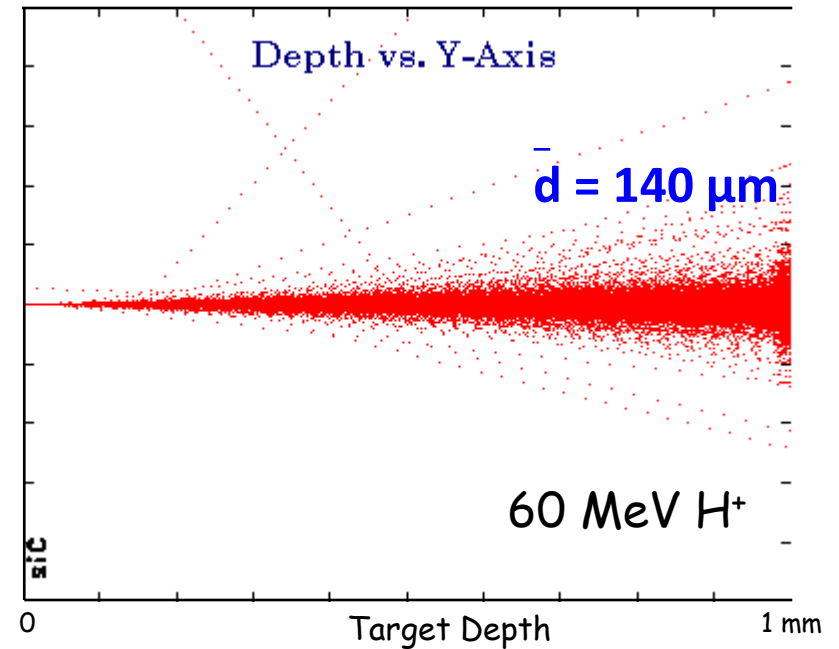
## Ion track effect



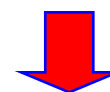
low distance between primary defects



defects recombination  
(LOW  $\epsilon$ )



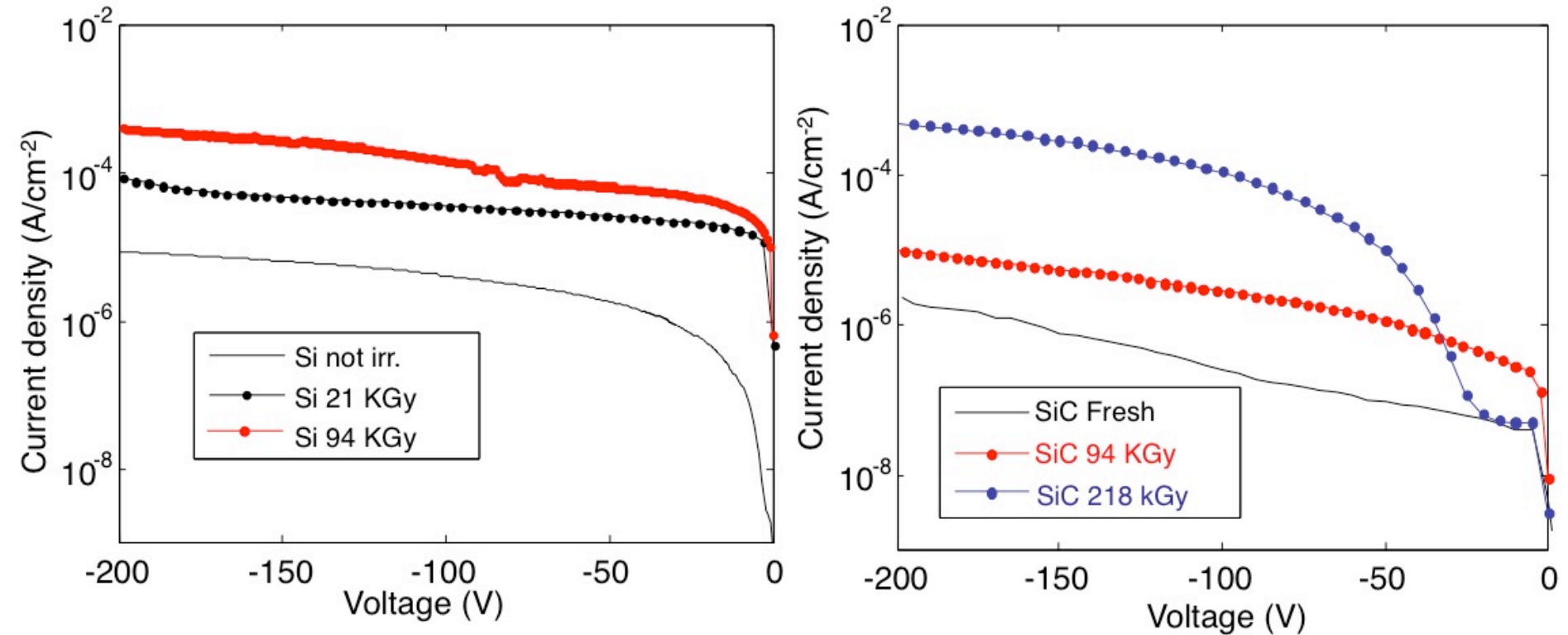
high distance between primary defects



no defects recombination  
(HIGH  $\epsilon$ )

# SiC vs. Si radiation hardness

740 MeV C<sup>+</sup>



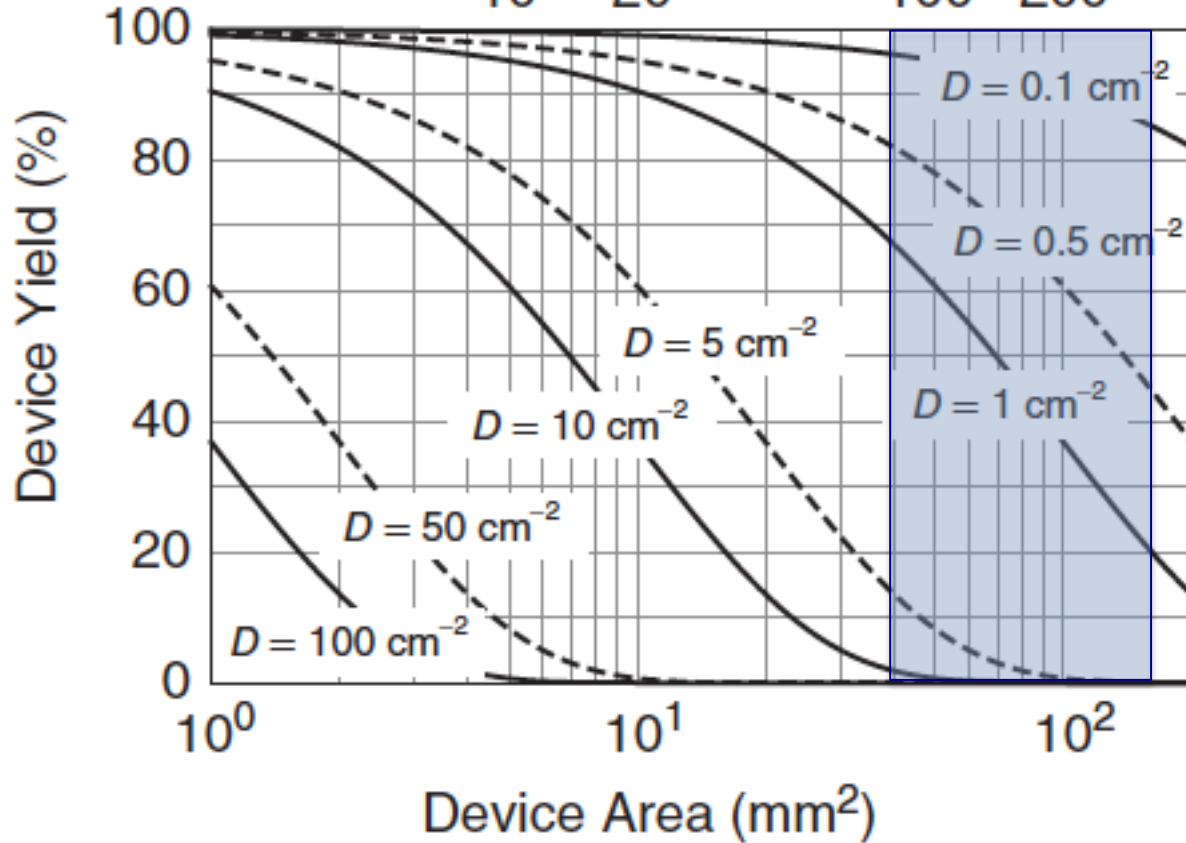
*S. Privitera et al. Material Science Forum (2016) in press.*



# Challenge for SiC detectors production: device area

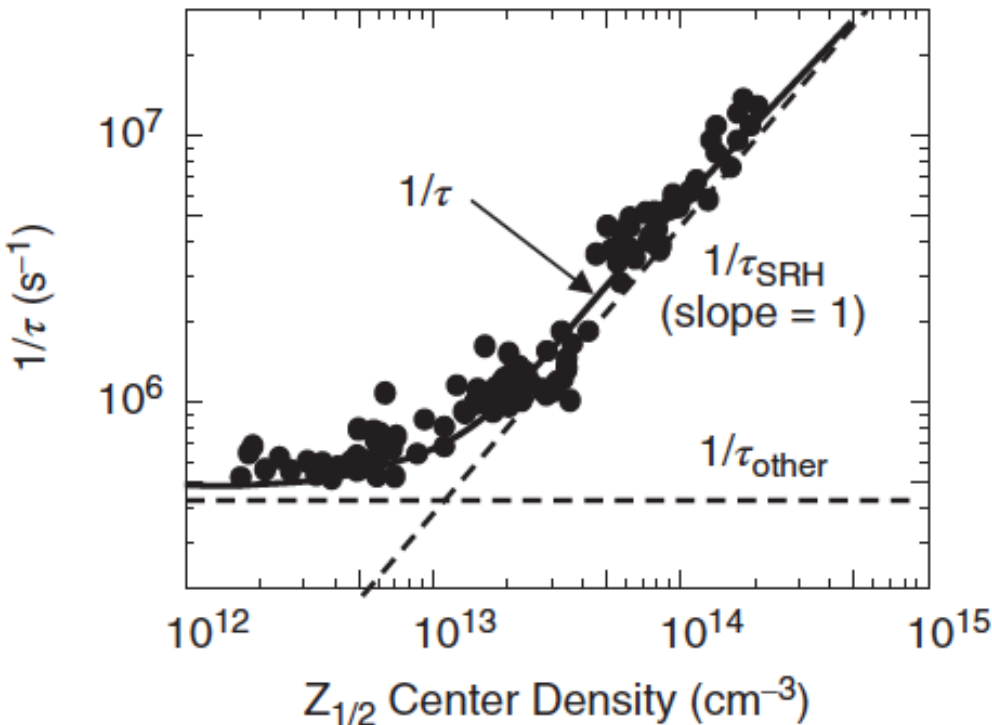
Current (A) ( $J = 200 \text{ A cm}^{-2}$ )

10 20 100 200

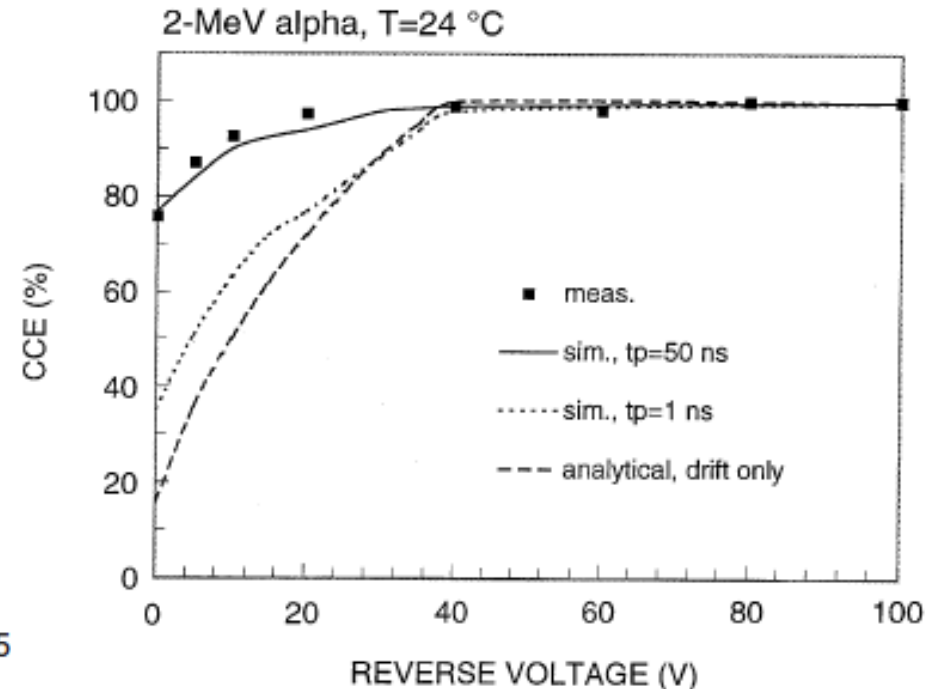


*For large area detectors  
a very low defects  
density  $D$  is needed*

# Challenge for SiC detectors production: carrier lifetime



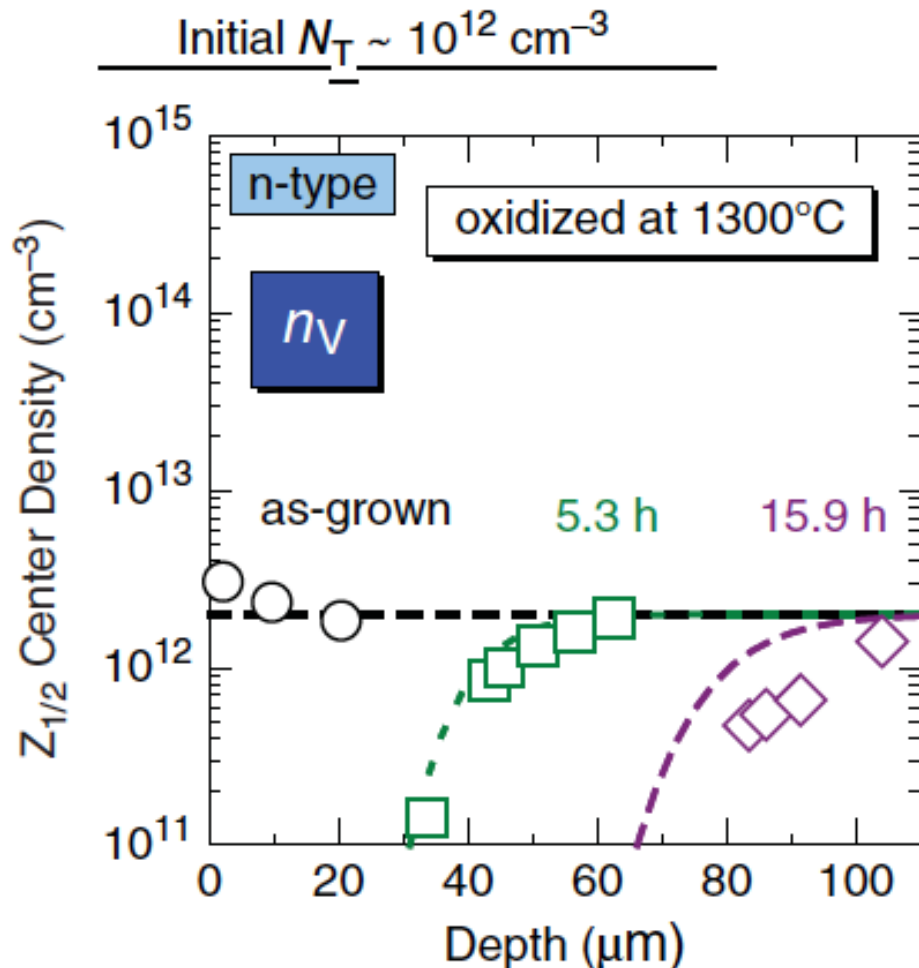
T. Kimoto et al. in "Silicon carbide epitaxy" (Ed. F. La Via, Research Signapost)



G. Verzellesi et al. / Nuclear Instruments and Methods in Physics Research A 476 (2002) 717–721

*The carrier lifetime can have an influence on CCE at low reverse bias.*

# Challenge for SiC detectors production: carrier lifetime



*To reduce the carbon vacancies and increase the minority carrier lifetime a high temperature oxidation or an oxidation and a subsequent high temperature annealing should be done*

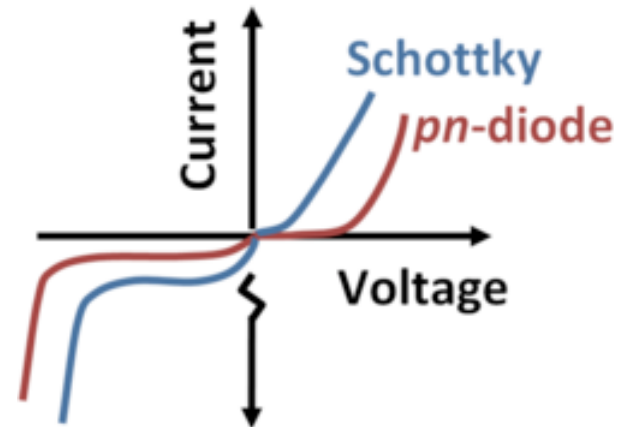
T. Kimoto et al. in "Silicon carbide epitaxy"  
(Ed. F. La Via, Research Signapost)

# Summary

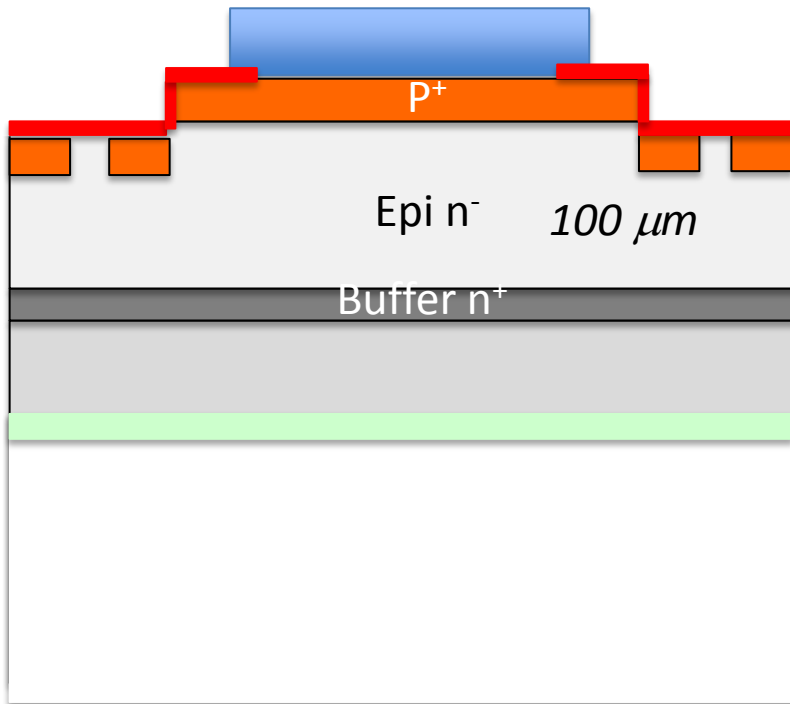
- SiC is extremely interesting for high radiation hardness detectors.
- High linearity and high resolution detectors have been demonstrated.
- The ion irradiation introduces point defects (*low fluence regime*) or cluster of point defects (*high fluence regime*).
  - Deactivation of dopant
  - Increase of the leakage current
- The efficiency in the introduction of point defects strongly depends on the energy.

# Outlook

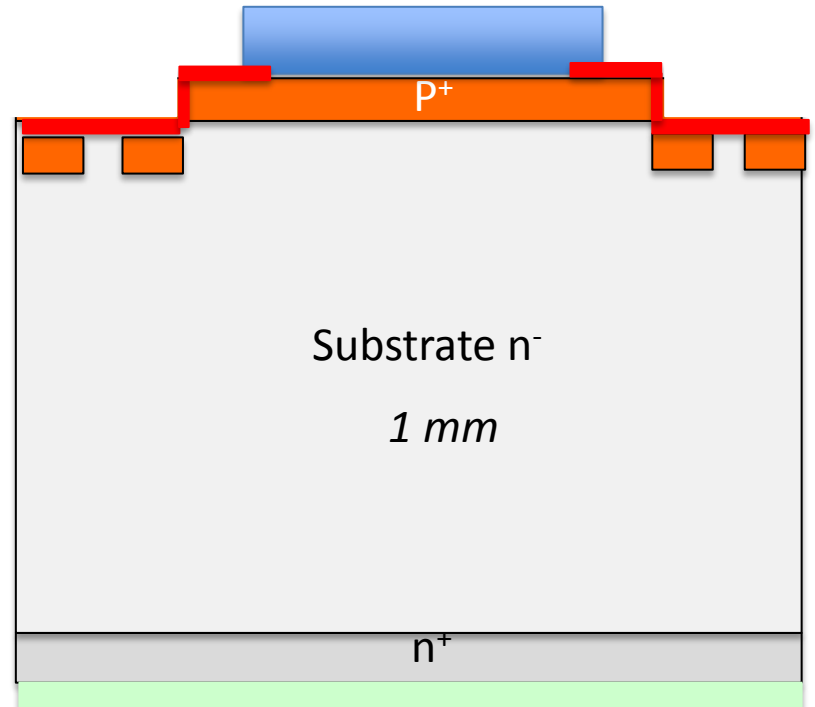
- For the realization of high energy ions detectors the main difficulty is reach the low defects density ( $<1 \text{ cm}^2$ ) needed to obtain a reasonable yield ( $>50\%$ ).
- Carrier lifetime can have an influence on the CCE at low voltage and then a high temperature oxidation process should be done to reduce the traps.
- The P/N junctions show a lower reverse leakage current with respect to the Schottky diodes at high voltage and then these kind of detectors will be used



# Outlook



$\Delta E$  detector



E detector

**Thank you for the attention**